

Title (en)
SEMICONDUCTOR STORAGE COMPONENT WITH A PLURALITY OF STORAGE CHIPS IN A SHARED CASING

Title (de)
HALBLEITER-SPEICHERBAUTEIL MIT MEHREREN SPEICHERCHIPS IN EINER GEMEINSAMEN UMHÜLLUNG

Title (fr)
COMPOSANT DE MEMORISATION A SEMI-CONDUSTEUR COMPORTANT PLUSIEURS PUCES MEMOIRES DANS UNE ENVELOPPE COMMUNE

Publication
EP 0744084 A1 19961127 (DE)

Application
EP 95908875 A 19950206

Priority
• DE 9500155 W 19950206
• DE 4403733 A 19940207

Abstract (en)
[origin: WO9521459A1] A semiconductor storage component comprises a plurality of storage chips (C) of the same or different storage types (DRAM, SRAM, E(E)PROM, etc.) which are secured to a shared substrate (T) and connected to its outer terminals (A) via electrical connections (B), in which an outer terminal (A) of the substrate is precisely allocated to each contact point (K) or each storage chip (C). In a first embodiment, the substrate (T) fitted with several storage chips (C) has a casing (U) leaving its outer terminals (A) free and may be secured to a module plate (M). In a second embodiment, the substrate (T) with several storage chips (C) is secured to a module plate (M) and covered with a moulding (F) or a potting compound (H) to the side of the substrate (T) away from the module plate in such a way that the coating (U) on the part of the module plate (M) beneath the substrate (T) and the moulding (F) or potting compound (H) also comprises the outer terminals (A) of the substrate.

IPC 1-7
H01L 23/495; **H01L 23/31**; **H01L 21/56**; **G11C 5/00**; **H01L 25/065**

IPC 8 full level
H01L 23/28 (2006.01); **G11C 5/00** (2006.01); **H01L 21/56** (2006.01); **H01L 23/31** (2006.01); **H01L 23/495** (2006.01); **H01L 25/00** (2006.01); **H01L 25/04** (2006.01); **H01L 25/065** (2006.01); **H01L 25/07** (2006.01); **H01L 25/18** (2006.01); **H05K 1/18** (2006.01)

CPC (source: EP KR)
G11C 5/025 (2013.01 - EP); **H01L 21/565** (2013.01 - EP); **H01L 23/3107** (2013.01 - EP); **H01L 23/495** (2013.01 - KR); **H01L 23/49572** (2013.01 - EP); **H01L 23/49575** (2013.01 - EP); **H01L 24/97** (2013.01 - EP); **H01L 24/45** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/49** (2013.01 - EP); **H01L 2224/05553** (2013.01 - EP); **H01L 2224/05554** (2013.01 - EP); **H01L 2224/45144** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/48247** (2013.01 - EP); **H01L 2224/48465** (2013.01 - EP); **H01L 2224/49175** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/97** (2013.01 - EP); **H01L 2924/01078** (2013.01 - EP); **H01L 2924/01079** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP); **H05K 1/181** (2013.01 - EP)

Citation (search report)
See references of WO 9521459A1

Designated contracting state (EPC)
AT DE FR GB IE IT NL

DOCDB simple family (publication)
WO 9521459 A1 19950810; EP 0744084 A1 19961127; JP H09508496 A 19970826; KR 970700940 A 19970212; TW 354859 B 19990321

DOCDB simple family (application)
DE 9500155 W 19950206; EP 95908875 A 19950206; JP 52031995 A 19950206; KR 19960704286 A 19960807; TW 84100691 A 19950126